TECHNICAL DATA SHEET



ATROX™ 800HT2V

Electrically and Highly Thermally Conductive Die Attach Adhesive

ATROX™ 800HT2V is a thermosetting conductive die attach adhesive with very high thermal conductivity designed for high power semiconductor packages. ATROX™ 800HT2V has low resin bleed out and low condensable organics which ensure excellent package reliability.

TYPICAL PROPERTIES

MATERIAL PROPERTIES	METHOD	VALUE	REMARKS
A. Uncured			
Chemical type		Thermosetting	
Color	Visual	Grey	
Viscosity at 25°C at 5.0 RPM	ASTM D2196-99	~ 17,000 cps	Brookfield Spindle 51
Thixotropic index (0.5 RPM/5.0 RPM)	ASTM D2196-99	6.1	Brookfield Spindle 51
Pot Life @ 23°C (elapsed time for 25% increase in viscosity)	ISO 10364:1993	>24 hours	Brookfield Spindle 51
Storage Temperature		-40 °C	
Shelf Life @ -40 (°C/°F)		6 months	
B. Cured			
Glass Transition (Tan δ Max)	DMA	73 °C	
Modulus at 25°C	DMA	9.1 GPa	
Modulus at 260°C	DMA	1.9 GPa	
CTE 1 (below Tg)	TMA	30 ppm	
CTE 2 (above Tg)	TMA	80 ppm	
Thermal Conductivity: Bulk	Laser Flash	>130 W/mK	
Volume Resistivity	4-Point Probe	0.00002 Ohms	

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DIE SHEAR STRENGTH (3 mm x 3 mm)

A. Metallized Die

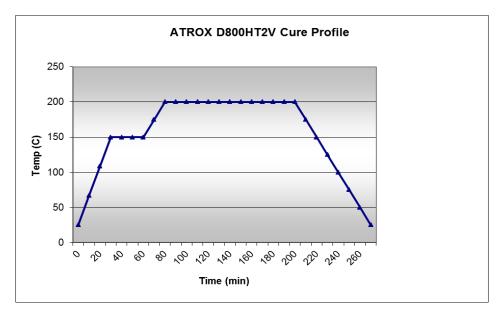
LEAD FRAME	CURE CONDITION	SHEAR TEMPERATURE	VALUE
Ag	RT to 150°C/30 min + 200°C/120 min	260°C	16.4 Kg-F
PPF (NiPdAu)	RT to 150°C/30 min + 200°C/120 min	260°C	15.9 Kg-F
Cu	RT to 150°C/30 min + 200°C/120 min	260°C	16.0 Kg-F

MATERIAL APPLICATION

ATROX™ 800HT2V is formulated to be applied using a time pressure pump equipped on most die bonders. The material should be consistently dispensed over time. Equipment settings need to be optimized for desired material deposition response based on model and configuration.

CURE

ATROXTM 800HT2V cures using ramp profile with 30 minute soak at 150°C + ramp 20 minute to 200°C and soak for 120 minutes. It is recommended that the cure schedule includes at ramp at 5 to 10°C and a controlled cooling cycle to minimize thermal stresses. Depending on thermal mass of application cure times may vary and should be optimized by the end user.



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RELIABILITY PERFORMANCE

ATROXTM 800HT2V is recommended for excellent reliability with stable Electrical and Thermal performance during MSL and Thermal Cycling. There is no limitation on die size for metalized die packages. However, it is recommended to consult with AAM Technical Service for optimizing critical parameters for specific packages.

It is also possible to assembly Bare Silicon dies up to 10 mm² with excellent Electrical and Thermal performance. For die sizes larger than 10 mm², kindly contact AAM for assistance.

CLEAN-UP

Uncured material may be cleaned from dispenser components and surfaces with a variety of solvents, including IPA, acetone, MEK, methylene chloride, etc. Always wash and dry thoroughly prior to re-use of the dispenser components. The cleaning technique should be active cleaning of the components – flush, wash or wipe, followed by a drying step to ensure a clean, dry surface. Do not soak since this can solubilize the hardener within the uncured resin and curing (very difficult to remove). Contact your equipment supplier to ensure the solvent is compatible with their components. Clean and maintain dispense valves as recommended by the equipment manufacturer.

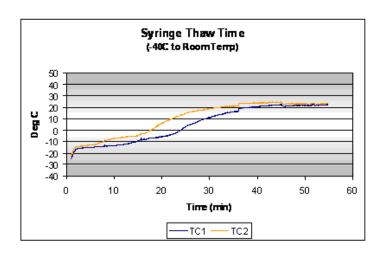
PACKAGING SIZES

ATROX™ 800HT2V is available in 5 or 10 cc EFD or Musashi syringes.

SHIPPING & STORAGE

Material is normally shipped in insulated boxes using dry ice to ensure that the ATROX™ 800HT2V maintains all its properties. On receipt, it must be ensured that dry-ice remnants are present in the insulated shipping box. If there is no dry ice, or if the material is not cold, then please contact Alpha Advanced Materials immediately. Exposing to elevated temperatures during shipment and storage will compromise on the performance aspect of the material adversely.

It is recommended to store the syringes of material at -40°C for a maximum shelf life of 6 months. It is recommended that the material be allowed to thaw before usage. Typical thawing times for 5cc and 10cc syringes are presented in chart below. Remove the syringe from freezer and set aside, allowing it to thaw at room temperature, until it reaches room temperature (90 minutes maximum for 30CC syringe). To prevent contamination of unused product, do not return any material to its original container.



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